- Dual Versions of the Popular '90A, 'LS90 and '93A, 'LS93

- '390, 'LS390 . . . Individual Clocks for A and B Flip-Flops Provide Dual ÷ 2 and ÷ 5 Counters

- '393, 'LS393 . . . Dual 4-Bit Binary Counter with Individual Clocks

- All Have Direct Clear for Each 4-Bit Counter

- Dual 4-Bit Versions Can Significantly Improve System Densities by Reducing Counter Package Count by 50%

- Typical Maximum Count Frequency . . . 35 MHz

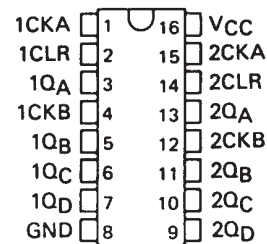- Buffered Outputs Reduce Possibility of Collector Commutation

description

Each of these monolithic circuits contains eight master-slave flip-flops and additional gating to implement two individual four-bit counters in a single package. The '390 and 'LS390 incorporate dual divide-by-two and divide-by-five counters, which can be used to implement cycle lengths equal to any whole and/or cumulative multiples of 2 and/or 5 up to divide-by-100. When connected as a bi-quinary counter, the separate divide-by-two circuit can be used to provide symmetry (a square wave) at the final output stage. The '393 and 'LS393 each comprise two independent four-bit binary counters each having a clear and a clock input. N-bit binary counters can be implemented with each package providing the capability of divide-by-256. The '390, 'LS390, '393, and 'LS393 have parallel outputs from each counter stage so that any submultiple of the input count frequency is available for system-timing signals.

Series 54 and Series 54LS circuits are characterized for operation over the full military temperature range of –55°C to 125°C; Series 74 and Series 74LS circuits are characterized for operation from 0°C to 70°C.
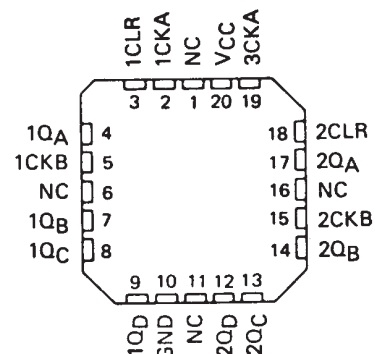
SN54390, SN54LS390 . . . J OR W PACKAGE
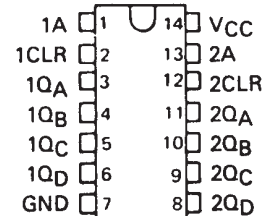**SN74390 . . . N PACKAGE**
SN74LS390 . . . D OR N PACKAGE
(TOP VIEW)

1CKA	1	16	V_{CC}
1CLR	2	15	2CKA
$1Q_A$	3	14	2CLR
1CKB	4	13	$2Q_A$
$1Q_B$	5	12	2CKB
$1Q_C$	6	11	$2Q_B$
$1Q_D$	7	10	$2Q_C$
GND	8	9	$2Q_D$

SN54LS390 . . . FK PACKAGE
(TOP VIEW)

Top: 1CLR, 1CKA, NC, V_{CC}, 3CKA (pins 3 2 1 20 19)

$1Q_A$	4	18	2CLR
1CKB	5	17	$2Q_A$
NC	6	16	NC
$1Q_B$	7	15	2CKB
$1Q_C$	8	14	$2Q_B$

Bottom: $1Q_D$, GND, NC, $2Q_D$, $2Q_C$ (pins 9 10 11 12 13)

SN54393, SN54LS393 . . . J OR W PACKAGE
SN74393 . . . N PACKAGE
SN74LS393 . . . D OR N PACKAGE
(TOP VIEW)

1A	1	14	V_{CC}
1CLR	2	13	2A
$1Q_A$	3	12	2CLR
$1Q_B$	4	11	$2Q_A$
$1Q_C$	5	10	$2Q_B$
$1Q_D$	6	9	$2Q_C$
GND	7	8	$2Q_D$

SN54LS393 . . . FK PACKAGE
(TOP VIEW)

Top: 1CLR, 1A, NC, V_{CC}, 2A (pins 3 2 1 20 19)

$1Q_A$	4	18	2CLR
NC	5	17	NC
$1Q_B$	6	16	$2Q_A$
NC	7	15	NC
$1Q_C$	8	14	$2Q_B$

Bottom: $1Q_D$, GND, NC, $2Q_D$, $2Q_C$ (pins 9 10 11 12 13)
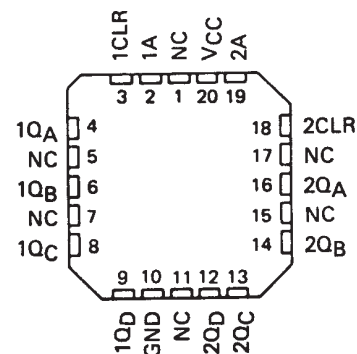
NC - No internal connection

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

SN54390, SN54LS390, SN54393, SN54LS393
SN74390, SN74LS390, SN74393, SN74LS393
DUAL 4-BIT DECADE AND BINARY COUNTERS

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FUNCTION TABLES

'390, 'LS390
BCD COUNT SEQUENCE
(EACH COUNTER)
(See Note A)

COUNT	OUTPUT			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H

'390, 'LS390
BI-QUINARY (5-2)
(EACH COUNTER)
(See Note B)

COUNT	OUTPUT			
	Q_A	Q_D	Q_C	Q_B
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	H	L	L	L
6	H	L	L	H
7	H	L	H	L
8	H	L	H	H
9	H	H	L	L

'393, 'LS393
COUNT SEQUENCE
(EACH COUNTER)

COUNT	OUTPUT			
	Q_D	Q_C	Q_B	Q_A
0	L	L	L	L
1	L	L	L	H
2	L	L	H	L
3	L	L	H	H
4	L	H	L	L
5	L	H	L	H
6	L	H	H	L
7	L	H	H	H
8	H	L	L	L
9	H	L	L	H
10	H	L	H	L
11	H	L	H	H
12	H	H	L	L
13	H	H	L	H
14	H	H	H	L
15	H	H	H	H

NOTES: A. Output Q_A is connected to input B for BCD count.
B. Output Q_D is connected to input A for bi-quinary count.
C. H = high level, L = low level.

logic diagrams (positive logic)

'390, 'LS390

logic symbols†

'390, 'LS390

'393, 'LS393

†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

logic diagrams (continued)

'393, 'LS393

INPUT A (1, 13)

Pin numbers shown are for D, J, N and W packages.

schematics of inputs and outputs
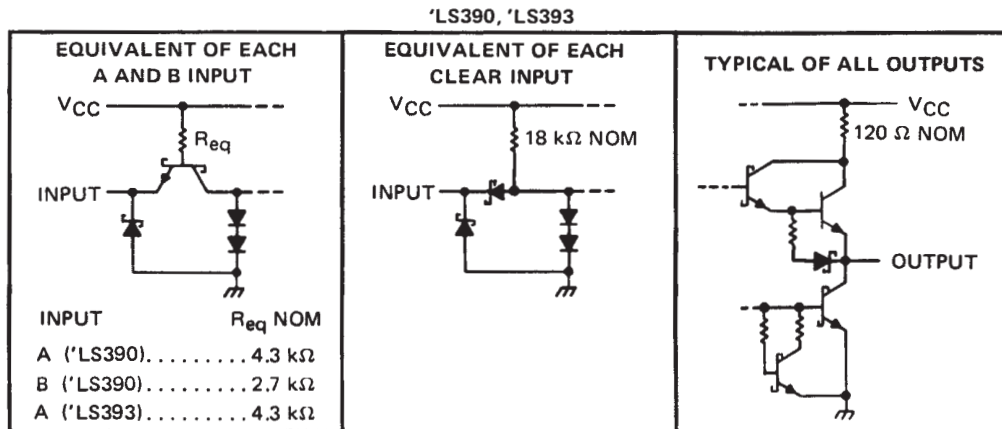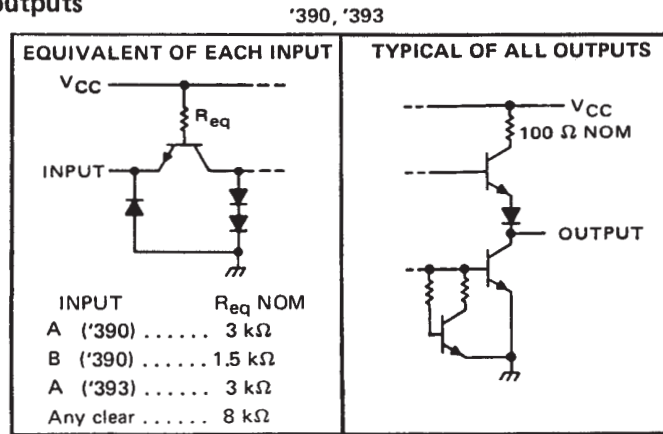
'390, '393

INPUT	R_{eq} NOM
A ('390)	3 kΩ
B ('390)	1.5 kΩ
A ('393)	3 kΩ
Any clear	8 kΩ

'LS390, 'LS393

INPUT	R_{eq} NOM
A ('LS390)	4.3 kΩ
B ('LS390)	2.7 kΩ
A ('LS393)	4.3 kΩ

TEXAS
INSTRUMENTS

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage . . . . 5.5 V
Operating free-air temperature range: SN54390, SN54393 . . . . −55°C to 125°C
 SN74390, SN74393 . . . . 0°C to 70°C
Storage temperature range . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

		SN54390 SN54393			SN74390 SN74393			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}				−800			−800	μA
Low-level output current, I_{OL}				16			16	mA
Count frequency, f_{count}	A input	0		25	0		25	MHz
	B input	0		20	0		20	
Pulse width, t_w	A input high or low	20			20			ns
	B input high or low	25			25			
	Clear high	20			20			
Clear inactive-state setup time, t_{su}		25↓			25↓			ns
Operating free-air temperature, T_A		−55		125	0		70	°C

↓ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS[†]	'390			'393			UNIT
				MIN	TYP[‡]	MAX	MIN	TYP[‡]	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.8			0.8	V
V_{IK}	Input clamp voltage		V_{CC} = MIN, I_I = −12 mA			−1.5			−1.5	V
V_{OH}	High-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OH} = −800 μA	2.4	3.4		2.4	3.4		V
V_{OL}	Low-level output voltage		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V, I_{OL} = 16 mA¶		0.2	0.4		0.2	0.4	V
I_I	Input current at maximum input voltage		V_{CC} = MAX, V_I = 5.5 V			1			1	mA
I_{IH}	High-level input current	Clear	V_{CC} = MAX, V_I = 2.4 V			40			40	μA
		Input A				80			80	
		Input B				120				
I_{IL}	Low-level input current	Clear	V_{CC} = MAX, V_I = 0.4 V			−1			−1	mA
		Input A				−3.2			−3.2	
		Input B				−4.8				
I_{OS}	Short-circuit output current[§]	SN54'	V_{CC} = MAX	−20		−57	−20		−57	mA
		SN74'		−18		−57	−18		−57	
I_{CC}	Supply current		V_{CC} = MAX, See Note 2		42	69		38	64	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.
[§] Not more than one output should be shorted at a time.
¶ The Q_A outputs of the '390 are tested at I_{OL} = 16 mA plus the limit value for I_{IL} for the B input. This permits driving the B input while maintaining full fan-out capability.
NOTE 2: I_{CC} is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'390 MIN	'390 TYP	'390 MAX	'393 MIN	'393 TYP	'393 MAX	UNIT
f_{max}	A	Q_A		25	35		25	35		MHz
	B	Q_B		20	30					
t_{PLH}	A	Q_A			12	20		12	20	ns
t_{PHL}					13	20		13	20	
t_{PLH}	A	Q_C of '390	C_L = 15 pF,		37	60		40	60	ns
t_{PHL}		Q_D of '393	R_L = 400 Ω,		39	60		40	60	
t_{PLH}	B	Q_B	See Note 3		13	21				ns
t_{PHL}			and		14	21				
t_{PLH}	B	Q_C	Figure 1		24	39				ns
t_{PHL}					26	39				
t_{PLH}	B	Q_D			13	21				ns
t_{PHL}					14	21				
t_{PHL}	Clear	Any			24	39		24	39	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PARAMETER MEASUREMENT INFORMATION

VOLTAGE WAVEFORMS

FIGURE 1

NOTE A: Input pulses are supplied by a generator having the following characteristics $t_r \leqslant 5$ ns, $t_f \leqslant 5$ ns, PRR = 1 MHz, duty cycle = 50%, $Z_{out} \approx 50$ ohms.

TEXAS
INSTRUMENTS

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

SN54390, SN54LS390, SN54393, SN54LS393
SN74390, SN74LS390, SN74393, SN74LS393
DUAL 4-BIT DECADE AND BINARY COUNTERS

SDLS107 – OCTOBER 1976 – REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . 7 V

Clear input voltage . . . . 7 V

Any A or B clock input voltage . . . . 5.5 V

Operating free-air temperature range: SN54LS390, SN54LS393 . . . . −55°C to 125°C

SN74LS390, SN74LS393 . . . . 0°C to 70°C

Storage temperature range . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54LS390 SN54LS393			SN74LS390 SN74LS393			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}			4.5	5	5.5	4.75	5	5.25	V
High-level output current, I_{OH}					−400			−400	µA
Low-level output current, I_{OL}					4			8	mA
Count frequency, f_{count}		A input	0		25	0		25	MHz
		B input	0		12.5	0		12.5	
Pulse width, t_w		A input high or low	20			20			ns
		B input high or low	40			40			
		Clear high	20			20			
Clear inactive-state setup time, t_{su}			25↓			25↓			ns
Operating free-air temperature, T_A			−55		125	0		70	°C

↓ The arrow indicates that the falling edge of the clock pulse is used for reference.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		SN54LS'			SN74LS'			UNIT
				MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IH}	High-level input voltage			2			2			V
V_{IL}	Low-level input voltage					0.7			0.8	V
V_{IK}	Input clamp voltage	V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = V_{IL}max, I_{OH} = −400 µA		2.5	3.4		2.7	3.4		V
V_{OL}	Low-level output voltage	V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = 0.8 V,	I_{OL} = 4 mA¶		0.25	0.4		0.25	0.4	V
			I_{OL} = 8 mA¶					0.35	0.5	
I_I	Input current at maximum input voltage	Clear	V_{CC} = MAX	V_I = 7 V			0.1			0.1	mA
		Input A		V_I = 5.5 V			0.2			0.2	
		Input B					0.4			0.4	
I_{IH}	High-level input current	Clear	V_{CC} = MAX, V_I = 2.7 V				0.02			0.02	mA
		Input A					0.1			0.1	
		Input B					0.2			0.2	
I_{IL}	Low-level input current	Clear	V_{CC} = MAX, V_I = 0.4 V				−0.4			−0.4	mA
		Input A					−1.6			−1.6	
		Input B					−2.4			−2.4	
I_{OS}	Short-circuit output current§	V_{CC} = MAX		−20		−100	−20		−100	mA
I_{CC}	Supply current	V_{CC} = MAX, See Note 2	'LS390		15	26		15	26	mA
			'LS393		15	26		15	26	

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

§ Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

¶ The Q_A outputs of the 'LS390 are tested at I_{OL} = MAX plus the limit value for I_{IL} for the clock B input. This permits driving the clock B input while maintaining full fan-out capability.

NOTE 2: I_{CC} is measured with all outputs open, both clear inputs grounded following momentary connection to 4.5 V, and all other inputs grounded.

TEXAS INSTRUMENTS

switching characteristics, V_{CC} = 5 V, T_A = 25°C

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS390			'LS393			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	A	Q_A		25	35		25	35		MHz
	B	Q_B		12.5	20					
t_{PLH}	A	Q_A			12	20		12	20	ns
t_{PHL}					13	20		13	20	
t_{PLH}	A	Q_C of 'LS390	C_L = 15 pF,		37	60		40	60	ns
t_{PHL}		Q_D of 'LS393	R_L = 2 kΩ,		39	60		40	60	
t_{PLH}	B	Q_B	See Note 4 and Figure 2		13	21				ns
t_{PHL}					14	21				
t_{PLH}	B	Q_C			24	39				ns
t_{PHL}					26	39				
t_{PLH}	B	Q_D			13	21				ns
t_{PHL}					14	21				
t_{PHL}	Clear	Any			24	39		24	39	ns

NOTE 4: Load circuits and voltage waveforms are shown in Section 1.

PARAMETER MEASUREMENT INFORMATION

VOLTAGE WAVEFORMS

FIGURE 2

NOTE A: Input pulses are supplied by a generator having the following characteristics $t_r \leq 15$ ns, $t_f \leq 6$ ns, PRR = 1 MHz, duty cycle = 50 %, $Z_{out} \approx 50$ ohms.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
7802601EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
7802601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
7802601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
JM38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
JM38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
JM38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
JM38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
JM38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
JM38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
M38510/32701B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32701B2A	Samples
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
M38510/32701BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32701BEA	Samples
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
M38510/32702B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	JM38510/ 32702B2A	Samples
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
M38510/32702BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BCA	Samples
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
M38510/32702BDA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702BDA	Samples
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
M38510/32702SDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 32702SDA SNV54LS393W	Samples
SN54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SN54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS390J	Samples
SN54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS390J	Samples
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS393J	Samples
SN54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54LS393J	Samples
SN74390N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74390N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74393N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74393N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS390	Samples
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS390N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS390N	Samples
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Samples
SN74LS390NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS390	Samples
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LS393DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LS393	Samples
SN74LS393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	0 to 70		
SN74LS393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS393N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	0 to 70		
SN74LS393NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74LS393N	Samples
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Samples
SN74LS393NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74LS393	Samples
SNJ54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54393J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54393W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54393W	OBSOLETE	CFP	W	14		TBD	Call TI	Call TI	-55 to 125		
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 390FK	Samples
SNJ54LS390FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 390FK	Samples
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
SNJ54LS390J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601EA SNJ54LS390J	Samples
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples
SNJ54LS390W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	7802601FA SNJ54LS390W	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 393FK	Samples
SNJ54LS393FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54LS 393FK	Samples
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393J	Samples
SNJ54LS393J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393J	Samples
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393W	Samples
SNJ54LS393W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54LS393W	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54393, SN54LS390, SN54LS393, SN54LS393-SP, SN74393, SN74LS390, SN74LS393 :

- Catalog: SN74393, SN74LS390, SN74LS393, SN54LS393

- Military: SN54393, SN54LS390, SN54LS393

- Space: SN54LS393-SP

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS390NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS393DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LS393NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS390NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74LS393DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74LS393NSR	SO	NS	14	2000	367.0	367.0	38.0

FK (S−CQCC−N**)   LEADLESS CERAMIC CHIP CARRIER
28 TERMINAL SHOWN

NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)

0.020 (0,51) / 0.010 (0,25)

0.020 (0,51) / 0.010 (0,25)

0.080 (2,03) / 0.064 (1,63)

0.055 (1,40) / 0.045 (1,14)

0.045 (1,14) / 0.035 (0,89)

0.028 (0,71) / 0.022 (0,54)

0.050 (1,27)

0.045 (1,14) / 0.035 (0,89)

4040140/D 01/11

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a metal lid.
         D.   Falls within JEDEC MS−004

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D (R−PDSO−G16)　　　　　　　　　　　　　　　PLASTIC SMALL OUTLINE

0.394 (10,00)
0.386 (9,80)
⚠C

16　　　　　　　　　　　　　9

1　　　　　　　　　　　　　8

Pin 1
Index Area

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)　⚠D

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)　0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−6/M　06/11

NOTES:　A.　All linear dimensions are in inches (millimeters).
　　　　B.　This drawing is subject to change without notice.
　　⚠C　Body length does not include mold flash, protrusions, or gate burrs.　Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
　　⚠D　Body width does not include interlead flash.　Interlead flash shall not exceed 0.017 (0,43) each side.
　　　　E.　Reference JEDEC MS−012 variation AC.

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D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x1,27

16x0,55

14x1,27

16x1,50

5,40

5.40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0,07
All Around

4211283−4/E 08/12

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Publication IPC−7351 is recommended for alternate designs.
         D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
             contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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MECHANICAL DATA

DIM / PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

B

14   8

C

1   7

$\dfrac{0.065\ (1,65)}{0.045\ (1,14)}$

0.005 (0,13) MIN

$\dfrac{0.060\ (1,52)}{0.015\ (0,38)}$

A

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

$\dfrac{0.026\ (0,66)}{0.014\ (0,36)}$

0.100 (2,54)

0°−15°

$\dfrac{0.014\ (0,36)}{0.008\ (0,20)}$

4040083/F 03/03

NOTES: A.   All linear dimensions are in inches (millimeters).
           B.   This drawing is subject to change without notice.
           C.   This package is hermetically sealed with a ceramic lid using glass frit.
           D.   Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
           E.   Falls within MIL STD 1835 GDIP1−T14, GDIP1−T16, GDIP1−T18 and GDIP1−T20.

W (R−GDFP−F14)   CERAMIC DUAL FLATPACK

Base and Seating Plane

0.260 (6,60)
0.235 (5,97)

0.045 (1,14)
0.026 (0,66)

0.008 (0,20)
0.004 (0,10)

0.080 (2,03)
0.045 (1,14)

0.280 (7,11) MAX

0.019 (0,48)
0.015 (0,38)

1   14

0.050 (1,27)

0.390 (9,91)
0.335 (8,51)

0.005 (0,13) MIN
4 Places

7   8

0.360 (9,14)
0.250 (6,35)

0.360 (9,14)
0.250 (6,35)

4040180−2/F 04/14

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package can be hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only.
         E.   Falls within MIL STD 1835 GDFP1−F14

W (R−GDFP−F16)   CERAMIC DUAL FLATPACK

Base and Seating Plane

0.045 (1,14)
0.026 (0,66)

0.285 (7,24)
0.245 (6,22)

0.008 (0,20)
0.004 (0,10)

0.080 (2,03)
0.055 (1,40)

0.305 (7,75) MAX

1   16

0.019 (0,48)
0.015 (0,38)

0.430 (10,92)
0.370 (9,40)

0.050 (1,27)

0.005 (0,13) MIN
4 Places

8   9

0.360 (9,14)
0.250 (6,35)

0.360 (9,14)
0.250 (6,35)

4040180−3/F 04/14

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. This package can be hermetically sealed with a ceramic lid using glass frit.
         D. Index point is provided on cap for terminal identification only.
         E. Falls within MIL STD 1835 GDFP2−F16

D (R−PDSO−G14)   PLASTIC SMALL OUTLINE

0.344 (8,75)
0.337 (8,55)
⟨C⟩

14   8

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) ⟨D⟩

1   7

Pin 1
Index Area

0.050 (1,27)   0.020 (0,51)
                    0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−5/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
          B. This drawing is subject to change without notice.
       ⟨C⟩ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
       ⟨D⟩ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
          E. Reference JEDEC MS−012 variation AB.

D (R–PDSO–G14)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

←12x1,27

←14x0,55

←12x1,27

14x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

—0,60

1,55

Example
Solder Mask Opening
(See Note E)

—0.07
All Around

4211283–3/E 08/12

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Publication IPC–7351 is recommended for alternate designs.
          D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
               contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
          E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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N (R–PDIP–T**) PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) △D

0.045 (1,14) / 0.030 (0,76) △D

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

14/18 Pin Only
20 Pin vendor option △D

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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